General Description
The HXT8201 VCSEL driver is a key component for compact, robust, low-power optical transmitter modules. In conjunction with the VCSEL, the chip handles the complete digital-to-optical conversion, including CML input, laser driver, drive control, and supervision. Standard silicon technology and a small number of additional components allow for cost-effective and compact assemblies.

Applications
• 100G to 25G Ethernet SR Fan-out Modules
• 25G Ethernet SR / 32G Fibre Channel
• InfiniBand 25G EDR Transceivers / AOC
• Proprietary multi-channel optical modules

Features
• Low power consumption of 118mW per channel while delivering 5mA average and 5mA modulation current
• User selectable: Input equalization, output peaking, polarity inversion, interrupt masks
• Compatible with common cathode and isolated VCSEL arrays
• 2-wire, \(^{\text{I}}^{\text{C}}\) compatible control interface
• Up to 10mA \(I_{\text{AVG}}\) and 10mA \(I_{\text{MOD}}\) current
• Suitable for TO Can applications
• SFP MSA Compatible

Ordering Information

<table>
<thead>
<tr>
<th>Part</th>
<th>Temp Range</th>
<th>Pin-Package</th>
</tr>
</thead>
<tbody>
<tr>
<td>HXT8201-DNT</td>
<td>0°C to +85°C</td>
<td>Bare Die* 1105 x 900µm</td>
</tr>
<tr>
<td>HXT8201-EVB</td>
<td>Room Temp</td>
<td>Evaluation Board</td>
</tr>
</tbody>
</table>

* Nominal Size: Actual die size may be slightly larger/smaller

For price, delivery schedules, and to place orders, please contact IDT: [www.IDT.com/go/sales](http://www.IDT.com/go/sales)

Device Diagram

![Device Diagram](image-url)
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